



Soft Material-Enabled Electronics for Medicine, Healthcare, and Human-Machine Interfaces

Guest Editors:

Dr. Woon-Hong Yeo

Woodruff School of Mechanical Engineering, Coulter Department of Biomedical Engineering, Georgia Tech, Atlanta, GA, USA

Prof. Dr. Jae-Woong Jeong

School of Electrical Engineering, Korea Advanced Institute of Science and Technology (KAIST), Daejeon, Korea

Message from the Guest Editors

Soft, functional materials enable comfortable, low-profile electronic systems, including sensors, stimulators, and actuators, for applications in medicine, healthcare, and human-machine interfaces. This Special Issue focuses on the use of soft, hybrid, functional materials to design and develop unobtrusive, multifunctional wearable and implantable electronics for biomedical applications. We invite full papers, communications, and reviews that cover one or several of the listed keywords below.

Keywords

Deadline for manuscript submissions:
closed (31 October 2019)

- soft material
- wearable electronics
- implantable electronics
- biosensing
- diagnostics
- health monitoring
- human-machine interface





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Editor-in-Chief

Prof. Dr. Maryam Tabrizian

1. Department of Biomedical Engineering, Faculty of Medicine and Health Sciences, McGill University, Montreal, QC H3A 2B6, Canada

2. Faculty of Dentistry and Oral Health Sciences, McGill University, 3640 Rue University, Montreal, QC H3A 0C7, Canada

Message from the Editor-in-Chief

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Contact Us

Materials Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
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